

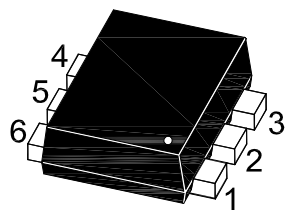
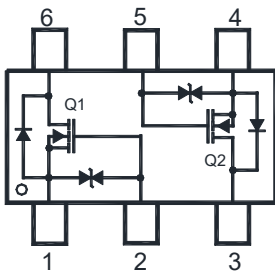
MMFTN3008KDE-AH

Dual N-Channel Enhancement Mode MOSFET

Features

- AEC-Q101 is Qualified
- Low threshold voltage
- Halogen and Antimony Free(HAF),
RoHS compliant
- Typical ESD Protection HBM Class 1C

Classification	Voltage Range(V)
0A	< 125
0B	125 to < 250
1A	250 to < 500
1B	500 to < 1000
1C	1000 to < 2000
2	2000 to < 4000
3A	4000 to < 8000
3B	≥ 8000



Q1: 1.Source 2.Gate 6.Drain
Q2: 4.Source 5.Gate 3.Drain
SOT-563 Plastic Package

Applications

- Portable appliances

Absolute Maximum Ratings($T_a = 25^{\circ}\text{C}$ unless otherwise specified)

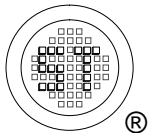
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current at $V_{GS} = 4.5\text{ V}$	I_D	$\begin{matrix} 350 \\ 230 \end{matrix}$	$\begin{matrix} \text{mA} \\ \text{mA} \end{matrix}$
Peak Drain Current, Pulsed ¹⁾	I_{DM}	1.4	A
Power Dissipation	P_D	400	mW
Operating Junction Temperature	T_j	- 55 to + 150	$^{\circ}\text{C}$
Storage Temperature Range	T_{stg}	- 55 to + 150	$^{\circ}\text{C}$

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ²⁾	$R_{\theta JA}$	313	$^{\circ}\text{C/W}$

¹⁾ Pulse Test: Pulse Width $\leq 100\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$, Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^{\circ}\text{C}$.

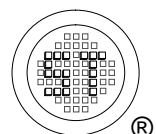
²⁾ Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.



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Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at $I_D = 250\ \mu\text{A}$	$V_{(BR)DSS}$	30	-	-	V
Drain-Source Leakage Current at $V_{DS} = 24\ \text{V}$	I_{DSS}	-	-	1	μA
Gate-Source Leakage at $V_{GS} = \pm 12\ \text{V}$	I_{GSS}	-	-	± 5	μA
Gate-Source Threshold Voltage at $V_{DS} = V_{GS}$, $I_D = 250\ \mu\text{A}$	$V_{GS(th)}$	0.6	-	1.1	V
Drain-Source On-State Resistance at $V_{GS} = 4.5\ \text{V}$, $I_D = 350\ \text{mA}$ at $V_{GS} = 2.5\ \text{V}$, $I_D = 200\ \text{mA}$ at $V_{GS} = 1.8\ \text{V}$, $I_D = 10\ \text{mA}$	$R_{DS(on)}$	- - -	- - -	1.4 2.1 3	Ω
DYNAMIC PARAMETERS					
Forward Transconductance at $V_{DS} = 10\ \text{V}$, $I_D = 350\ \text{mA}$	g_{fs}	-	650	-	mS
Input Capacitance at $V_{DS} = 25\ \text{V}$, $V_{GS} = 0\ \text{V}$, $f = 1\ \text{MHz}$	C_{iss}	-	31	-	pF
Output Capacitance at $V_{DS} = 25\ \text{V}$, $V_{GS} = 0\ \text{V}$, $f = 1\ \text{MHz}$	C_{oss}	-	10	-	pF
Reverse Transfer Capacitance at $V_{DS} = 25\ \text{V}$, $V_{GS} = 0\ \text{V}$, $f = 1\ \text{MHz}$	C_{rss}	-	7.5	-	pF
Total Gate Charge at $V_{DS} = 25\ \text{V}$, $I_D = 1\ \text{A}$, $V_{GS} = 10\ \text{V}$ at $V_{DS} = 25\ \text{V}$, $I_D = 1\ \text{A}$, $V_{GS} = 4.5\ \text{V}$	Q_g	- -	1.3 0.8	- -	nC
Gate Source Charge at $V_{DS} = 25\ \text{V}$, $I_D = 1\ \text{A}$, $V_{GS} = 10\ \text{V}$	Q_{gs}	-	0.5	-	nC
Gate Drain Charge at $V_{DS} = 25\ \text{V}$, $I_D = 1\ \text{A}$, $V_{GS} = 10\ \text{V}$	Q_{gd}	-	0.4	-	nC
Turn-On Delay Time at $V_{DS} = 30\ \text{V}$, $V_{GS} = 10\ \text{V}$, $I_D = 0.5\ \text{A}$, $R_L = 60\ \Omega$, $R_G = 25\ \Omega$	$t_{d(on)}$	-	5.5	-	ns
Turn-On Rise Time at $V_{DS} = 30\ \text{V}$, $V_{GS} = 10\ \text{V}$, $I_D = 0.5\ \text{A}$, $R_L = 60\ \Omega$, $R_G = 25\ \Omega$	t_r	-	3	-	ns
Turn-Off Delay Time at $V_{DS} = 30\ \text{V}$, $V_{GS} = 10\ \text{V}$, $I_D = 0.5\ \text{A}$, $R_L = 60\ \Omega$, $R_G = 25\ \Omega$	$t_{d(off)}$	-	6	-	ns
Turn-Off Fall Time at $V_{DS} = 30\ \text{V}$, $V_{GS} = 10\ \text{V}$, $I_D = 0.5\ \text{A}$, $R_L = 60\ \Omega$, $R_G = 25\ \Omega$	t_f	-	30	-	ns
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at $I_S = 0.5\ \text{A}$	V_{SD}	-	-	1.3	V
Body Diode Reverse Recovery Time at $I_S = 0.5\ \text{A}$, $di/dt = 100\ \text{A}/\mu\text{s}$	t_{rr}	-	42	-	ns
Body Diode Reverse Recovery Charge at $I_S = 0.5\ \text{A}$, $di/dt = 100\ \text{A}/\mu\text{s}$	Q_{rr}	-	41	-	nC



Electrical Characteristics Curves

Fig.1 Transfer Characteristic

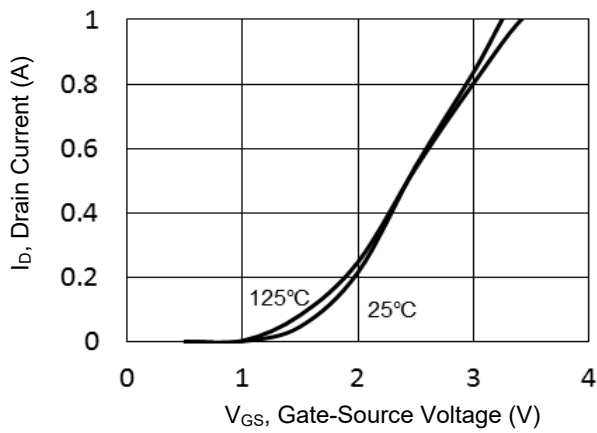


Fig.2 Output Characteristic

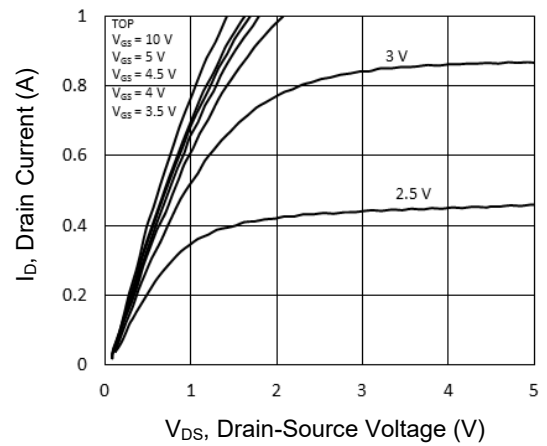


Fig.3 Normalized On-Resistance vs Temperature

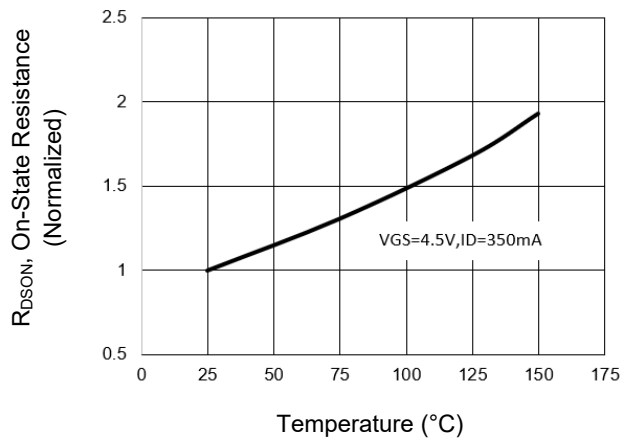


Fig.4 On-Resistance vs Gate-Source Voltage

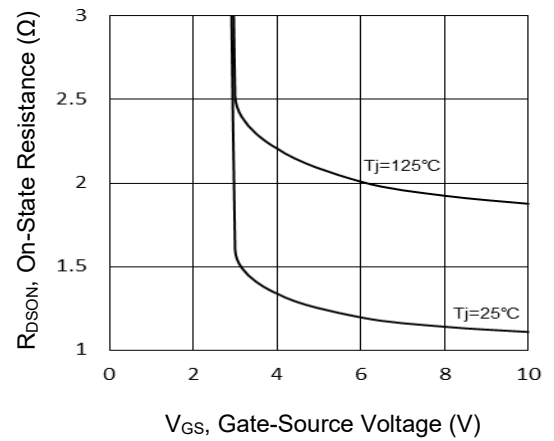


Fig.5 Junction Capacitance

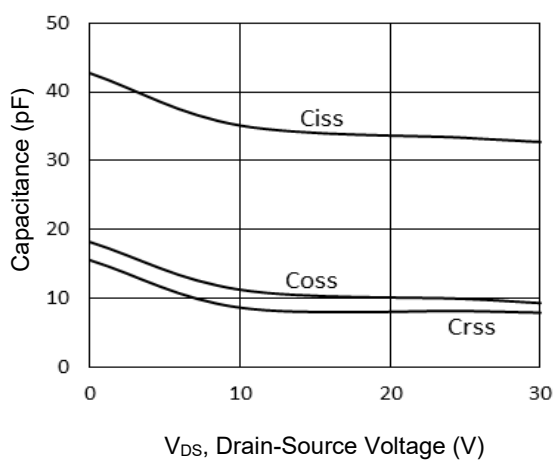
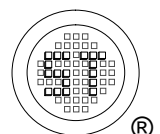
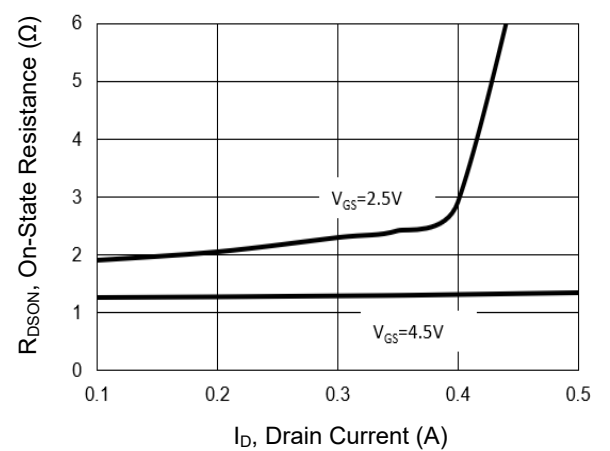


Fig.6 On-Resistance vs Drain Current



Electrical Characteristics Curves

Fig.7 B_{VDSS} vs Temperature

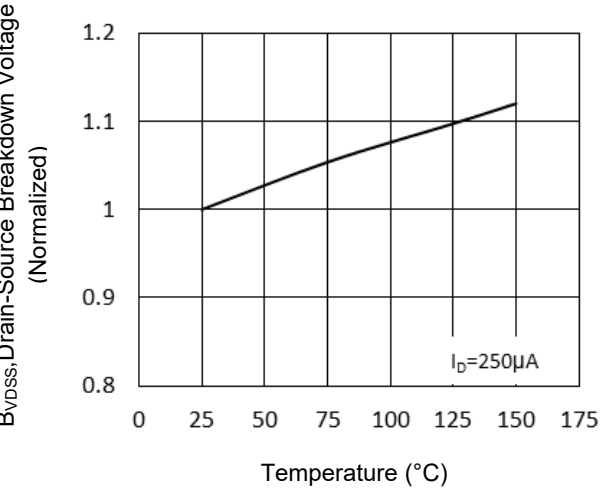


Fig.8 $V_{GS(th)}$ Variation vs Temperature

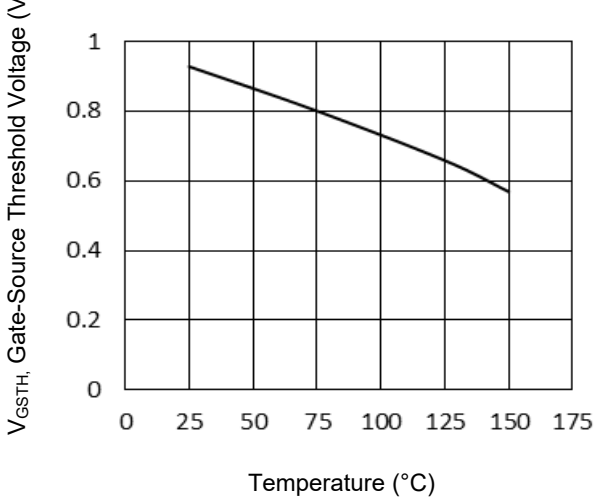


Fig.9 Forward Voltage

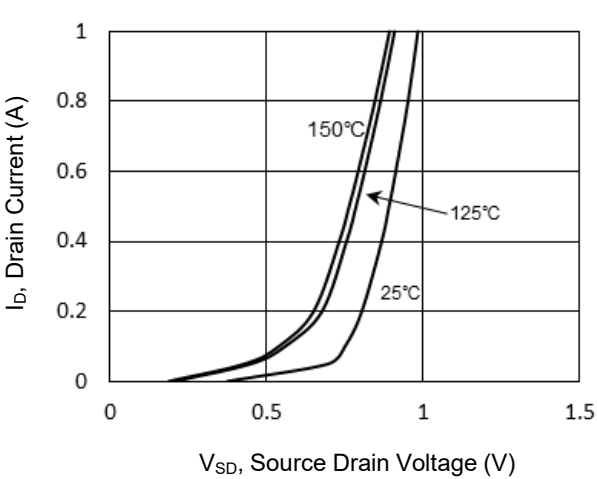
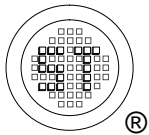
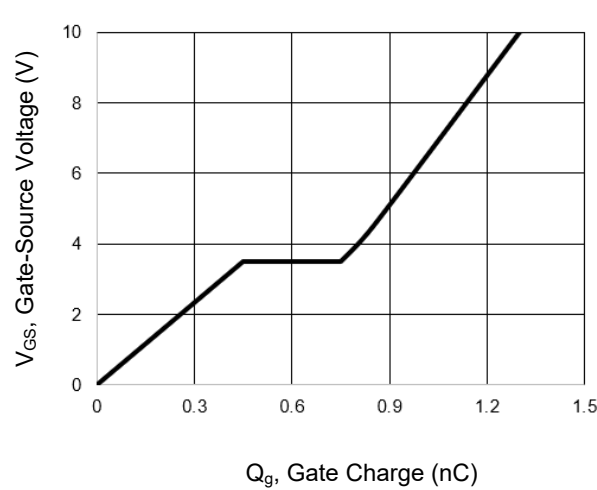


Fig.10 Gate Charge



Test Circuits

Fig.1-1 Switching times test circuit

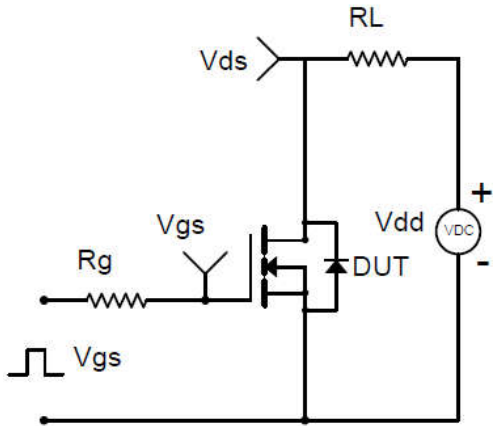


Fig.1-2 Switching Waveform

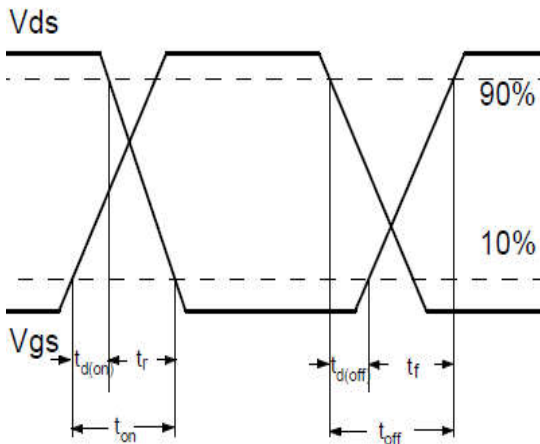


Fig.2-1 Gate charge test circuit

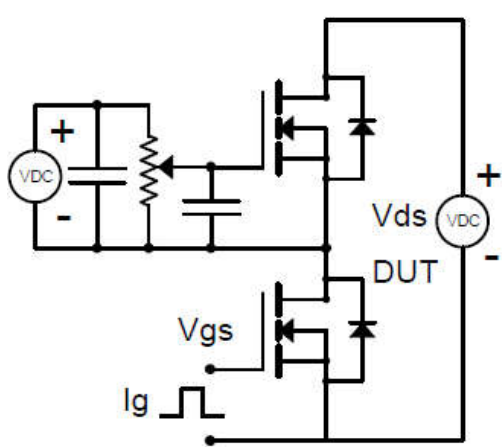
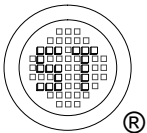
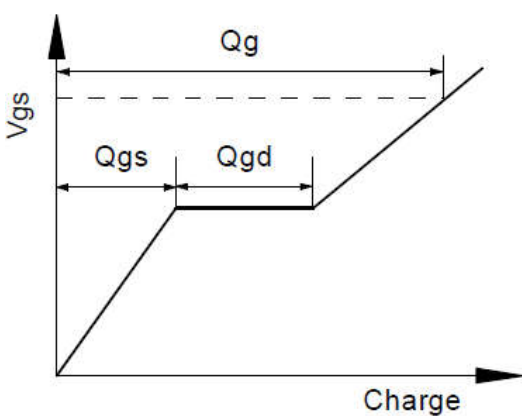


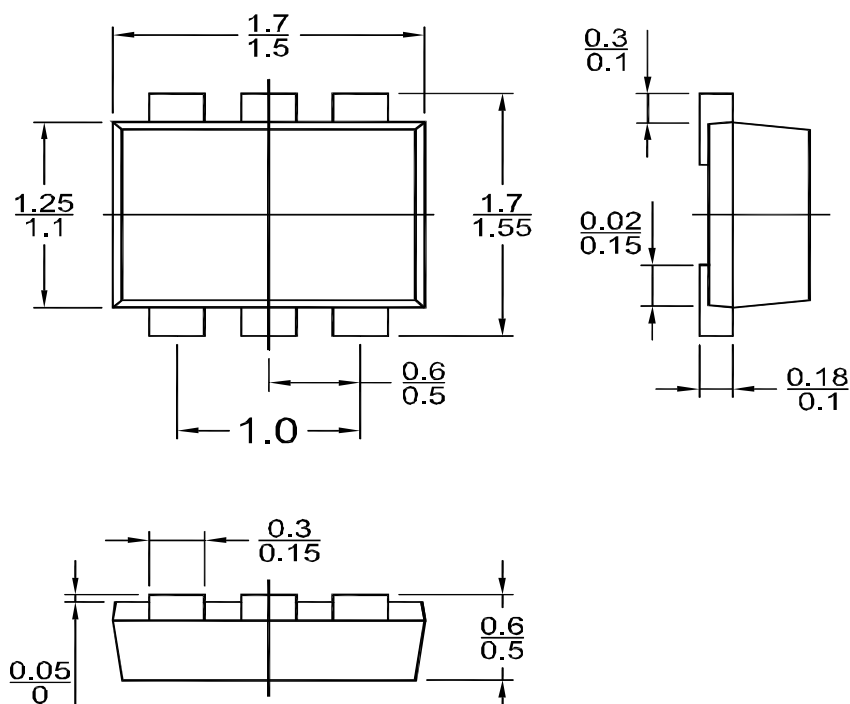
Fig.2-2 Gate charge waveform



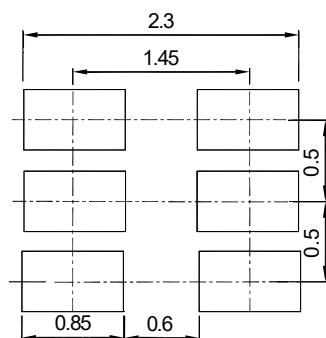
MMFTN3008KDE-AH

Package Outline Dimensions (Units: mm)

SOT-563



Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-563	8	4 ± 0.1	0.157 ± 0.004	178	7	4,000

Marking information

" MJ " = Part No.
" • " = HAF (Halogen and Antimony Free)
" YM " = Date Code Marking
" Y " = Year
" M " = Month
Font type: Arial

